DECLARED PROCESS LIST		ORIGINATOR : LAM			
SPACECRAFT:	HERSCHEL	DOC. NUMBER :	LAM/ELE/FTS/011009.01		
SYSTEM / EXPERIMENT :	SPIRE	SHEET No:	1/		
SUB SYSTEM:	FTS	ISSUE:	0.0		
		DATE:	09 – 10 - 2001		

Process	Process	Specification	Description /	Use and location	User	Associated	Criticality of	Approval /
ID		(incl. issue)	Identification		code	DML Items	process	Status
1	Surface mounted devices			Used for passive and active components in the warm electronics			low	
2	Through hole mounting devices			Used for passive and active components in both the warm electronic and the electronics located in the mechanism			low	
3	Hybrid mounting		Electrical bondings between dies and PCB	Used for optoelectronic components in the encoder head				
4								
5								
6								
7								
8								